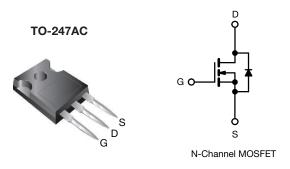
SiHG039N60E

Vishay Siliconix



E Series Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.034			
Q _g max. (nC)	126				
Q _{gs} (nC)	29				
Q _{gd} (nC)	28				
Configuration	Single				

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AC
Lead (Pb)-free and halogen-free	SiHG039N60E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-source voltage			V _{DS}	600	N/		
Gate-source voltage			V _{GS}	± 30	V		
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D -	63			
	VGS at 10 V	T _C = 100 °C		40	А		
Pulsed drain current ^a			I _{DM}	199			
Linear derating factor				2.9	W/°C		
Single pulse avalanche energy ^b			E _{AS}	633	mJ		
Maximum power dissipation			PD	357	W		
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	T _J = 125 °C		alı . /alt	70	\//mm		
Reverse diode dv/dt ^d		dv/dt	6.3	V/ns			
Soldering recommendations (peak temperature) ^c	For 10 s			260	°C		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 6.7 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C





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PARAMETER	SYMBOL	TYP.		ΜΔΧ				
	_			MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	- 40			°C/W			
Maximum junction-to-case (drain)	R _{thJC}	- 0.35						
SPECIFICATIONS (T _J = 25 $^{\circ}$ C,	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDITION	IS	MIN.	TYP.	MAX.	UNI
Static		•			•	•	•	
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250	μA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D =	= 1 mA	-	0.65	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	V _{DS} = V _{GS} , I _D = 250 μA		3	-	5	V
		$V_{GS} = \pm 20 V$			-	-	± 100	nA
Gate-source leakage	I _{GSS}	$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μA	
		V _{DS} = 600 V, V _{GS} = 0 V		-	-	1		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J	= 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 32 A		-	0.034	0.039	Ω
Forward transconductance	9 _{fs}	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 32 \text{ A}$		-	17	-	S	
Dynamic								
Input capacitance	C _{iss}		V _{GS} = 0 V,		-	4369	-	
Output capacitance	C _{oss}	$V_{DS} = 100 V,$ f = 1 MHz $V_{DS} = 0 V to 480 V, V_{GS} = 0 V$		-	178	-	pF	
Reverse transfer capacitance	C _{rss}			-	7	-		
Effective output capacitance, energy related ^a	C _{o(er)}			-	143	-		
Effective output capacitance, time related ^b	C _{o(tr)}			-	870	-		
Total gate charge	Qg				-	84	126	
Gate-source charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 32 \text{ A}, V_{DS} = 480 \text{ V}$		-	29	-	nC	
Gate-drain charge	Q _{gd}			-	28	-		
Turn-on delay time	t _{d(on)}				-	79	119	
Rise time	t _r	V_{DD} = 480 V, I_D = 32 A, V_{GS} = 10 V, R_g = 24 Ω		: A,	-	126	190	1
Turn-off delay time	t _{d(off)}			-	176	264	ns	
Fall time	t _f			-	94	141		
Gate input resistance	Rg	f = 1 MHz, open drain			0.3	0.7	1.4	Ω
Drain-Source Body Diode Characterist								
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	50	•	
Pulsed diode forward current	I _{SM}			-	-	155	A	
			T _J = 25 °C, I _S = 32 A, V _{GS} = 0 V					
Diode forward voltage	V _{SD}	T _J = 25 °C	C, I _S = 32 A, V _G	_{is} = 0 V	-	-	1.2	V

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

Q_{rr}

 I_{RRM}

b. Coss(tr) is a fixed capacitance that gives the same charging time as Coss while VDS is rising from 0 % to 80 % VDSS

Reverse recovery charge

Reverse recovery current

2

 $\begin{array}{l} T_J=25~^\circ C,~I_F=I_S=32~A,\\ di/dt=100~A/\mu s,~V_R=25~V \end{array}$

24.2

-

μC

А

12.1

30

-

_



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

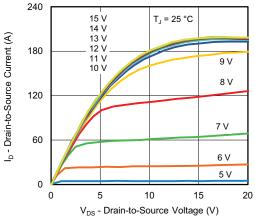


Fig. 1 - Typical Output Characteristics

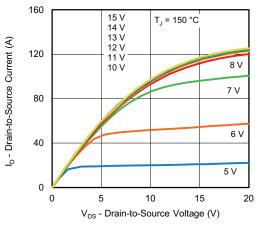


Fig. 2 - Typical Output Characteristics

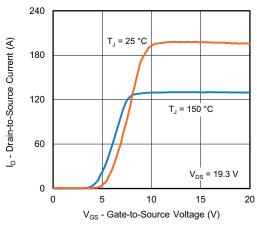


Fig. 3 - Typical Transfer Characteristics

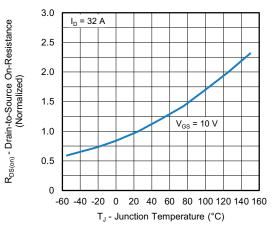


Fig. 4 - Normalized On-Resistance vs. Temperature

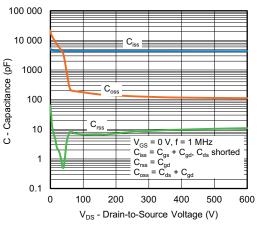
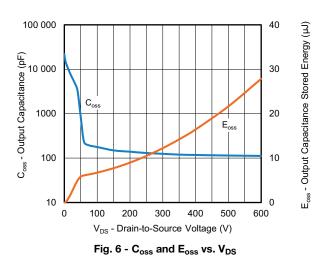


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



S18-0972-Rev. A, 01-Oct-2018

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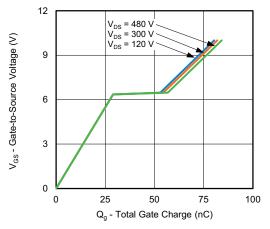


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

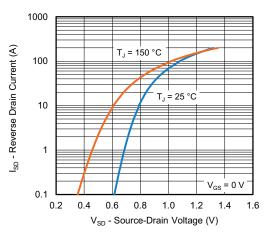


Fig. 8 - Typical Source-Drain Diode Forward Voltage

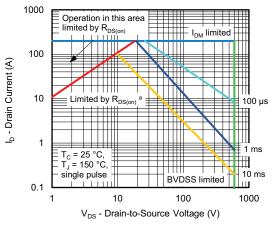


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

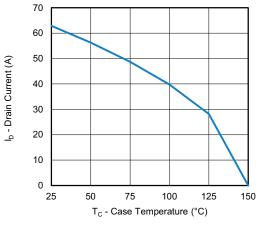


Fig. 10 - Maximum Drain Current vs. Case Temperature

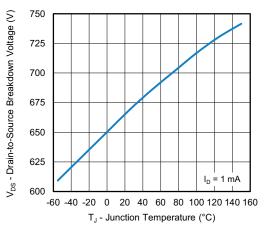
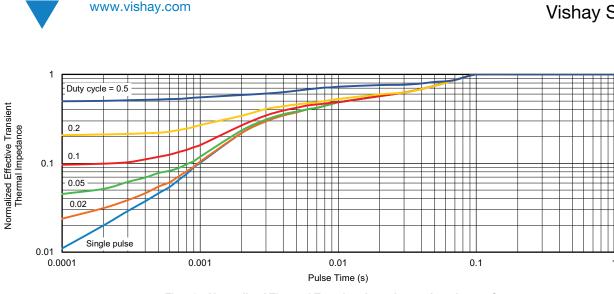


Fig. 11 - Temperature vs. Drain-to-Source Voltage

4

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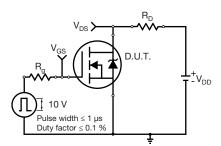


Fig. 13 - Switching Time Test Circuit

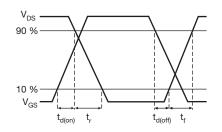


Fig. 14 - Switching Time Waveforms

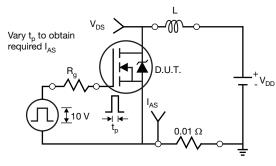


Fig. 15 - Unclamped Inductive Test Circuit

V_{DD} VDS AS

Fig. 16 - Unclamped Inductive Waveforms

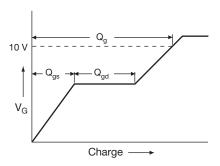


Fig. 17 - Basic Gate Charge Waveform

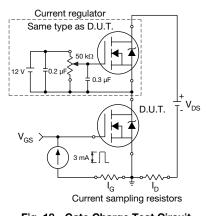


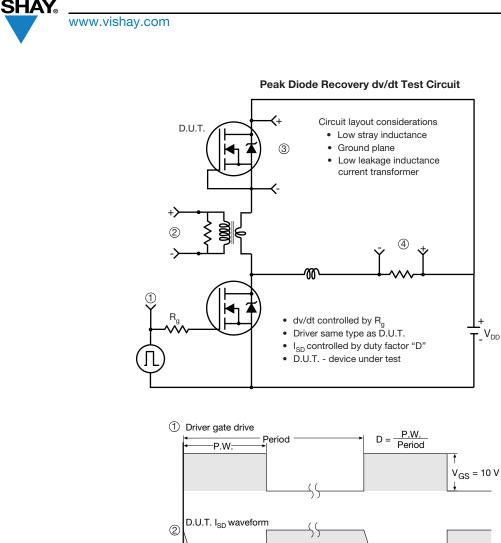
Fig. 18 - Gate Charge Test Circuit

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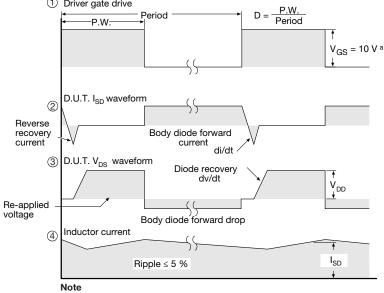
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a. $V_{GS} = 5$ V for logic level devices

Fig. 19 - For N-Channel

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